

ABSTRACT OF THE DISCLOSURE

An plating apparatus which can easily form a plated film having more uniform thickness on a surface, to be plate, of a material to be plated. The plating apparatus includes a holding portion having a heating portion for holding a material to be plated in such a state that a surface to be plated faces downward, and a plating bath for introducing an electroless plating liquid having a predetermined temperature into a plating chamber, and holding the electroless plating liquid while allowing the electroless plating liquid to overflow an overflow dam. The material which is by the holding portion, is brought into contact with the plating liquid in the plating bath to plate the material.

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